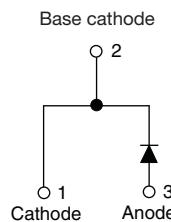


## Ultrafast Rectifier, 30 A FRED Pt®



### FEATURES

- Ultrafast and soft recovery
- Optimized forward voltage drop
- 175 °C maximum operating junction temperature
- Polyimide passivation
- Rugged design
- Good thermal performance
- AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	30 A
$V_R$	1200 V
$V_F$ at $I_F$ at 125 °C	2.05 V
$t_{rr}$	49 ns
$T_J$ max.	175 °C
Package	2L TO-220AC
Circuit configuration	Single

### DESCRIPTION / APPLICATIONS

Ultrafast recovery rectifiers designed with optimized performance of forward voltage drop, recovery time, and soft recovery. Polyimide passivated, planar structure, and the platinum doped life time control guarantee, ruggedness, reliability characteristics, and solid value proposition for efficiency and thermal performance.

These devices are intended for use in boost stage in the AC/DC section of SMPS, high frequency output rectification of battery charger, inverters for solar inverters, or as freewheeling diodes in motor drive.

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Repetitive peak reverse voltage	$V_{RRM}$		1200	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 100$ °C, $D = 0.50$	30	A
Repetitive peak forward current	$I_{FRM}$		60	A
Non-repetitive peak surge current	$I_{FSM}$	$T_C = 25$ °C, $t_p = 10$ ms, sine wave	240	A
Operating junction and storage temperature	$T_J$ , $T_{Stg}$		-55 to +175	°C

### ELECTRICAL SPECIFICATIONS ( $T_J = 25$ °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}$ , $V_R$	$I_R = 500$ µA	1200	-	-	V
Forward voltage	$V_F$	$I_F = 30$ A	-	2.15	2.68	
		$I_F = 30$ A, $T_J = 125$ °C	-	2.05	2.45	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	-	145	µA
		$T_J = 125$ °C, $V_R = V_R$ rated	-	-	320	
Junction capacitance	$C_T$	$V_R = 200$ V	-	29	-	pF
Series inductance	$L_S$	Measured to lead 5 mm from package body	-	8	-	nH

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0 \text{ A}$ , $dI_F/dt = 100 \text{ A}/\mu\text{s}$ , $V_R = 30 \text{ V}$	-	49	-	ns
		$T_J = 25^\circ\text{C}$	-	220	-	
		$T_J = 125^\circ\text{C}$	-	356	-	
Peak recovery current	$I_{RRM}$	$T_J = 25^\circ\text{C}$	-	8.2	-	A
		$T_J = 125^\circ\text{C}$	-	13.3	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25^\circ\text{C}$	-	900	-	nC
		$T_J = 125^\circ\text{C}$	-	2388	-	

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal resistance, junction to case	$R_{thJC}$	Typical socket mount	-	-	0.8	°C/W
Thermal resistance, junction to ambient	$R_{thJA}$		-	-	54	
Thermal resistance, case to heatsink	$R_{thCS}$		-	-	0.4	
Weight		Mounting surface, flat, smooth, and greased	-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Maximum junction and storage temperature range	$T_J, T_{Stg}$		-55	-	175	°C
Marking device		Case style: 2L TO-220AC	30ETU12TH			

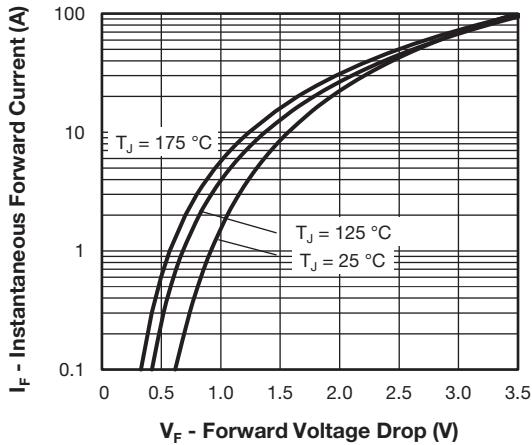


Fig. 1 - Typical Forward Voltage Drop Characteristics

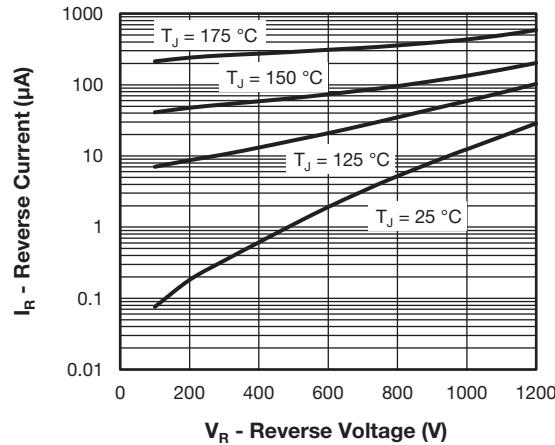


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

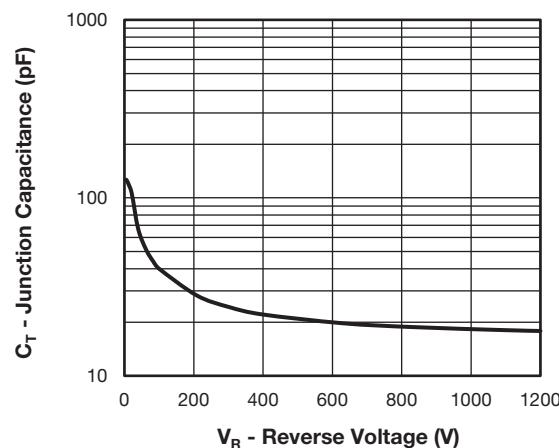


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

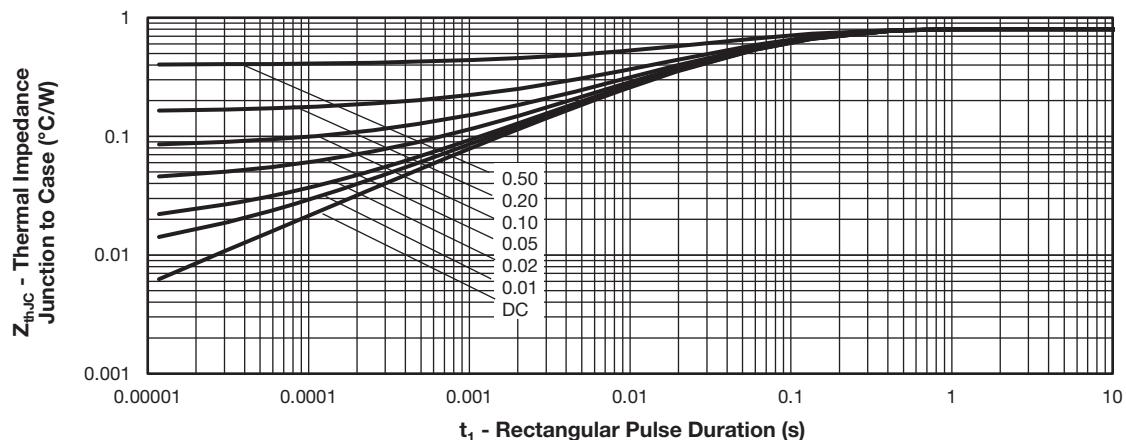


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

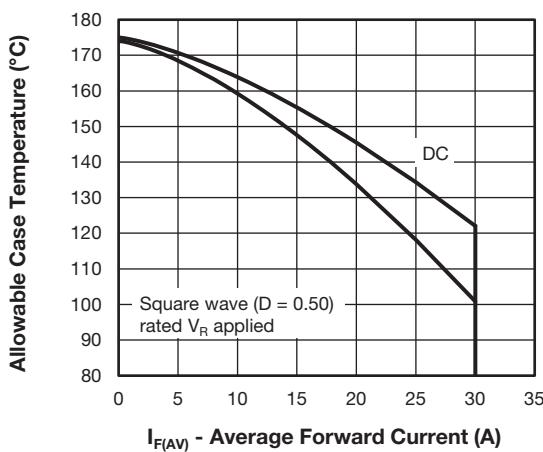


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

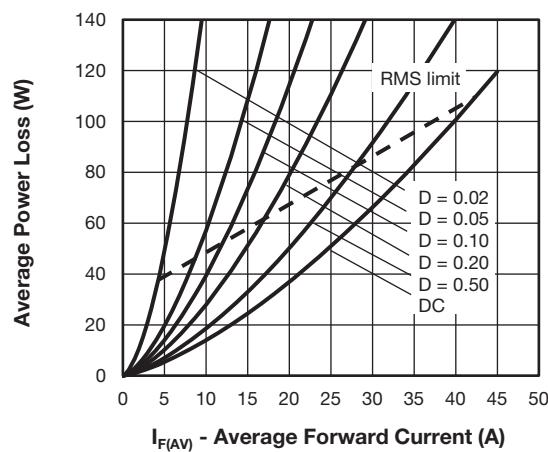


Fig. 6 - Forward Power Loss Characteristics

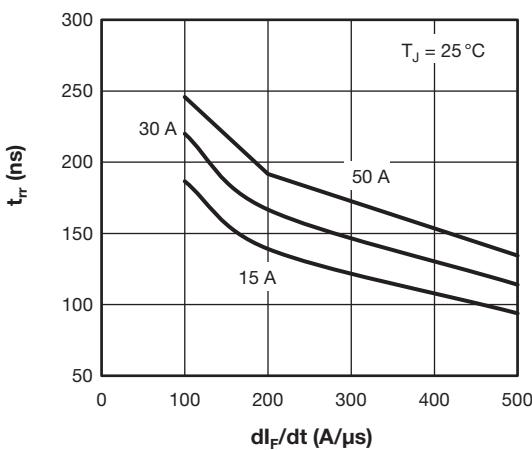


Fig. 7 - Typical Reverse Recovery Time vs.  $dI_F/dt$

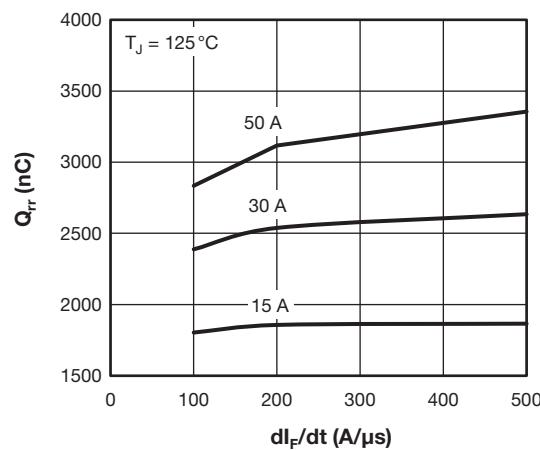


Fig. 10 - Typical Stored Charge vs.  $dI_F/dt$

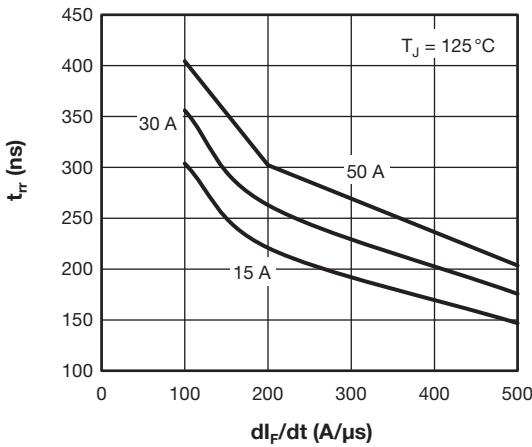


Fig. 8 - Typical Reverse Recovery Time vs.  $dI_F/dt$

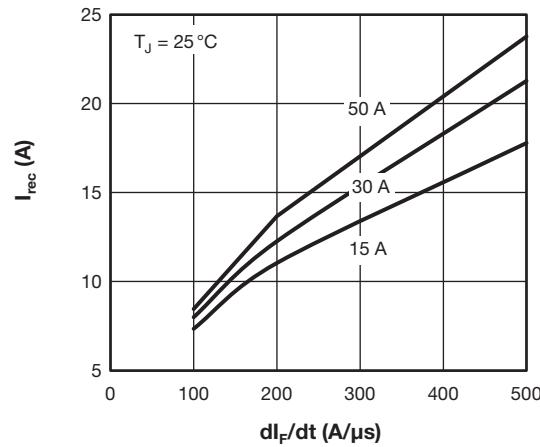


Fig. 11 - Typical Reverse Current vs.  $dI_F/dt$

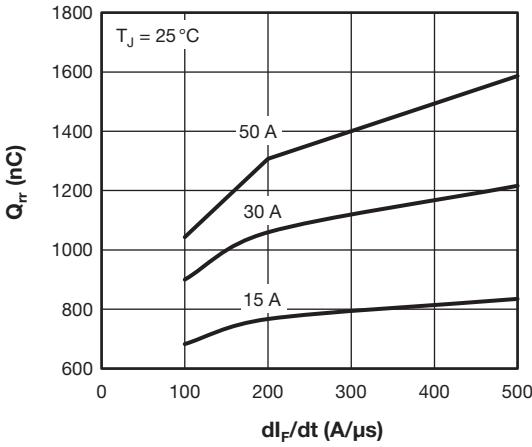


Fig. 9 - Typical Stored Charge vs.  $dI_F/dt$

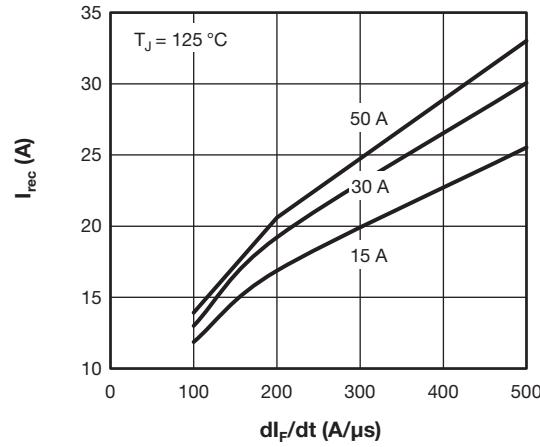
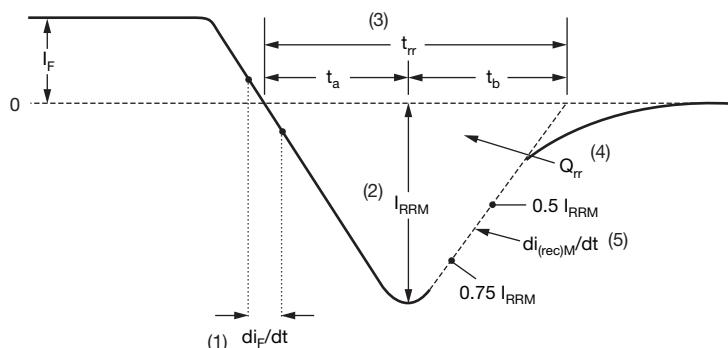


Fig. 12 - Typical Reverse Current vs.  $dI_F/dt$



(1)  $di_F/dt$  - rate of change of current through zero crossing

(4)  $Q_{rr}$  - area under curve defined by  $t_{rr}$  and  $I_{RRM}$

(2)  $I_{RRM}$  - peak reverse recovery current

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(3)  $t_{rr}$  - reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current.

(5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$

Fig. 13 - Reverse Recovery Waveform and Definitions

## ORDERING INFORMATION TABLE

Device code	VS-	30	E	T	U	12	T	H	N3
	1	2	3	4	5	6	7	8	9

- 1** - Vishay Semiconductors product
- 2** - Current rating 30 = 30 A
- 3** - E = single diode
- 4** - Package: T = TO-220AC
- 5** - U = ultrafast recovery
- 6** - Voltage rating (12 = 1200 V)
- 7** - T = True 2 pin TO-220
- 8** - H = AEC-Q101 qualified
- 9** - Environmental digit:

N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

### ORDERING INFORMATION (Example)

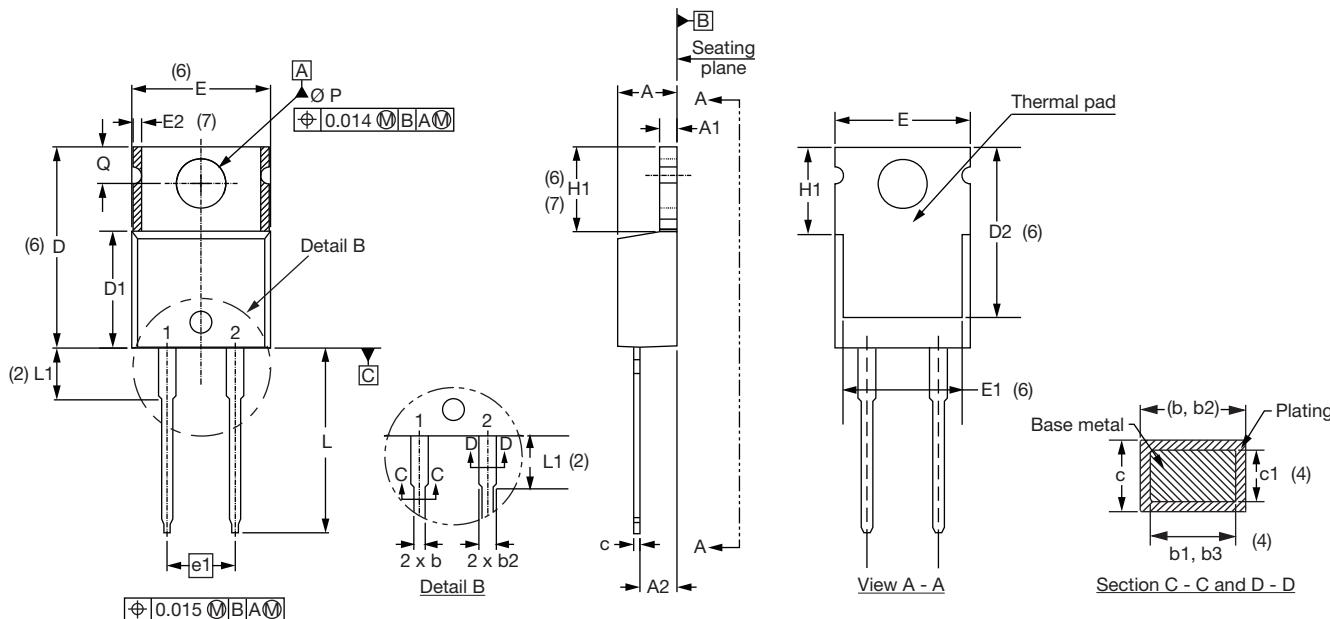
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-30ETU12THN3	50	1000	Antistatic plastic tube

### LINKS TO RELATED DOCUMENTS

Dimensions	2L TO-220AC	<a href="http://www.vishay.com/doc?96069">www.vishay.com/doc?96069</a>
Part marking information	2L TO-220AC	<a href="http://www.vishay.com/doc?95391">www.vishay.com/doc?95391</a>

## 2L TO-220AC

**DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES		SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183			E1	6.86	8.89	0.270	0.350	6
A1	1.14	1.40	0.045	0.055			E2	-	0.76	-	0.030	7
A2	2.56	2.92	0.101	0.115			e1	4.88	5.28	0.192	0.208	
b	0.69	1.01	0.027	0.040			H1	5.84	6.86	0.230	0.270	6, 7
b1	0.38	0.97	0.015	0.038	4		L	13.52	14.02	0.532	0.552	
b2	1.20	1.73	0.047	0.068			L1	3.32	3.82	0.131	0.150	2
b3	1.14	1.73	0.045	0.068	4		Ø P	3.54	3.73	0.139	0.147	
c	0.36	0.61	0.014	0.024			Q	2.60	3.00	0.102	0.118	
c1	0.36	0.56	0.014	0.022	4							
D	14.85	15.25	0.585	0.600	3							
D1	8.38	9.02	0.330	0.355								
D2	11.68	12.88	0.460	0.507	6							
E	10.11	10.51	0.398	0.414	3, 6							

### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC® TO-220, except D2, where JEDEC® minimum is 0.480"

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